I, Number	Hits	Search Text	DB	Time stamp
1	1752	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/08/08 19:59
2	11	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (ash$3 with atmospher$3 with pressure)	USPAT; US-PGPUB	2003/08/08 19:57
3	324	ash$3 with atmospher$3 with pressure	USPAT; US-PGPUB	2003/08/08 19:57
4	139	ash$3 with "atmospheric pressure"	USPAT; US-PGPUB	2003/08/08 19:57
5	76	ash$3 with "atmospheric pressure"	EPO; JPO; DERWENT	2003/08/08 19:58
6	1	c23c016$.ipc. and (ash$3 with "atmospheric pressure")	EPO; JPO; DERWENT	2003/08/08 19:59
7	11	(chamber with ash$3 with "atmospheric pressure")	EPO; JPO; DERWENT	2003/08/08 19:59
8	23	(ashing with "atmospheric pressure")	EPO; JPO; DERWENT	2003/08/08 20:00
-	208	(118/$.ccls. 156/345.$.ccls.) and ((monitor$3 determin$3 measure$3) with (particle particulate debris) with surface)	USPAT; US-PGPUB	2003/08/08 12:32
-	2550	(118/$.ccls. 156/345.$.ccls.) and ((monitor$3 determin$3 measure$3) with (thickness))	USPAT; US-PGPUB	2003/08/08 12:32
-	1414	(118/$.ccls. 156/345.$.ccls.) and ((monitor$3 measure$3) with (thickness))	USPAT; US-PGPUB	2003/08/08 12:32
-	113	(118/$.ccls. 156/345.$.ccls.) and ((monitor$3 measure$3) with (particle particulate debris) with surface)	USPAT; US-PGPUB	2003/08/08 13:09
-	9	5837094.URPN.	USPAT	2003/08/08 12:45
-	999	(monitor$3 measure$3 detect$3) with (particle particulate debris) with surface with (wafer substrate semiconductor)	USPAT; US-PGPUB	2003/08/08 19:50
-	48978	c23c016$.ipc.	EPO; JPO; DERWENT	2003/08/08 13:36
-	0	(monitor$3 measure$3 detect$3) with (particle particulate debris) with surface with (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/08/08 13:11
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/08/08 13:32
-	1752	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/08/08 19:50
-	105	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((monitor$3 detect$3 measur$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 13:36
-	48978	c23c016$.ipc.	EPO; JPO; DERWENT	2003/08/08 13:36
-	59	4693777.URPN.	USPAT	2003/08/08 13:55
-	103	c23c016$.ipc. and ((monitor$3 detect$3 measur$4) with (particle particulate dust))	EPO; JPO; DERWENT	2003/08/08 15:51
-	2	09/945,454	USPAT; US-PGPUB	2003/08/08 15:42
-	2	09/945454	USPAT; US-PGPUB	2003/08/08 15:42
-	121	((transfer$4 transport$3) with chamber) and ((monitor$3 detect$3 measur$4) with (particle particulate dust))	EPO; JPO; DERWENT	2003/08/08 15:54
-	2388	((transfer$4 transport$3) with chamber) and ((monitor$3 detect$3 measur$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 15:54
-	122	((transfer$4 transport$3) with chamber) with ((monitor$3 detect$3 measur$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 15:54
-	57	((transfer$4 transport$3) with chamber) with ((monitor$3 detect$3 measur$4) with (particle particulate dust))	EPO; JPO; DERWENT	2003/08/08 15:55
-	76	((transfer$4 transport$3) with chamber) same ((monitor$3 detect$3 measur$4) with (particle particulate dust))	EPO; JPO; DERWENT	2003/08/08 16:04

	194	((transfer$4 transport$3) with chamber) same ((monitor$3 detect$3 measur$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 16:28
-	2	118/719.ccls. and imahashi.in.	USPAT; US-PGPUB	2003/08/08 17:01
-	1	("5909276").PN.	USPAT; US-PGPUB	2003/08/08 20:03